

INTERNATIONAL STANDARD

NORME INTERNATIONALE



Printed board design, manufacture and assembly – Terms and definitions

Conception, fabrication et assemblage des cartes imprimées – Termes et définitions





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Printed board design, manufacture and assembly – Terms and definitions

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**PRINTED BOARD DESIGN, MANUFACTURE AND ASSEMBLY –
TERMS AND DEFINITIONS****FOREWORD**

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International Standard IEC 60194 has been prepared by subcommittee 91: Electronics assembly technology.

This sixth edition cancels and replaces the fifth edition, published in 2006 and constitutes a technical revision.

The main changes with respect to the previous edition are the following: Some two hundred terms and definitions have been updated, where applicable, and another two hundred new terms and definitions have been added.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1236/FDIS	91/1253/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

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INTRODUCTION

This International Standard has been structured in such a way that for each letter of the alphabet a new clause has been created. For the sake of comparison, the French version is aligned to the English sequence and thus follows the alphabetical order of the English version.

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PRINTED BOARD DESIGN, MANUFACTURE AND ASSEMBLY – TERMS AND DEFINITIONS

1 Scope

This International Standard defines the terminology used in the field of printed circuit boards and printed circuit board assembly products.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050-541:1990, *International Electrotechnical Vocabulary – Chapter 541: Printed circuits*

3 Terms and definitions

For the purposes of electronics assembly technology the terms and definitions from IEC 60050-541 as well as the following apply.

The terms have been classified according to the decimal classification code (DCC) as explained in Annex A.

4 A

54.1821

abrasion resistance

ability of a material to withstand surface wear

54.1318

abrasive trimming

adjusting the value of a film component by notching it with a finely adjusted stream of an abrasive material against the resistor surface

40.1727

absorption coefficient

for a parallel beam of specified radiation in a given substance, the quantity μ_{abs} describes the fraction of energy absorbed in passing through a thin layer of thickness Δx

Note 1 to entry: The absorption coefficient is primarily energy dependent.

Note 2 to entry: According to whether the thickness Δx is expressed in terms of length, mass per unit area, moles per unit area or atoms per unit area, it is called the linear, mass, molar or atomic absorption coefficient.

Note 3 to entry: This entry was numbered 393-14-46 in IEC 60050-393:2003.

[SOURCE: IEC 60050-395:2014, 395-01-26]